Revision history of Board Changes

Note

The xWR6843ISK and IWR6843ISK-ODS Rev.C is an 8-layer board mainly due to the addition of the 60-Pin Samtec connector added for direct DCA100EVM connector and the layout requirements for high speed LVDS traces routed to the connector. Rev B is still a valid reference for 6-layer board design

Board Revision	**Details of changes**	**Device version**
IWR6843ISK Rev A	Baseline document	ES1.0
IWR6843ISK Rev B	Module board could be plugged in both the orientation; ECO rolled in to design to fix this	ES1.0 and ES2.0 (Pre-production silicon)
IWR6843ISK Rev C	1. 2 CAN interface added onboard 2. USB added for data and power 3. 60 Pin Samtec connector added for direct DCA100EVM connector 4. Switch added for multiplexing SPI & UART, 5. SOP switches and buttons also added 6. CP2105 USB to UART added 7. PMIC changed to LP87524 to support 5V input	ES2.0 (RTM silicon)
IWR6843ISK Rev D	1. Additional capacitors added to improve power integrity 2. Change in EVM form factor	ES2.0 (RTM silicon)

Board Revision	Details of changes	Device version
IWR6843ISK-ODS Rev A	Baseline document	ES1.0 and ES2.0 (Pre-production silicon)
IWR6843ISK-ODS Rev B	Internal Release (Same as Rev C)	ES2.0 (RTM silicon)
IWR6843ISK-ODS Rev C	Feature additions: Support for Standalone mode of operation, USB powered, Direct connect to DCA1000 CANFD transceiver	ES2.0 (RTM silicon)
IWR6843ISK-ODS Rev D	Additional capacitors on the PMIC output to reduce the PMIC ripple (Design Database for reference only not Fabricated yet)	ES2.0 (RTM silicon)

Board Revision	Details of changes	Device version
MMWAVICBOOST Rev B	1. Module board could be plugged in both the orientation: ECO rolled in to design 2. SOP lines are not getting registered sometimes (Increased the reset time constant) 3. Make DNI for 12V path, Trace, DMM, Debug header and MiPI 60 pin connector (Most use case scenario) 4. SOP0 and SOP2 Silk text interchanged: Incorporated in the design	N/A